

Electronic Patent Application Fee Transmittal

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|---|---|-----------------|---------------|-----------------------------|
| Application Number: | 10719218 | | | |
| Filing Date: | 20-Nov-2003 | | | |
| Title of Invention: | STRUCTURE, MATERIAL, AND DESIGN FOR ASSEMBLING A LOW-K SI DIE TO ACHIEVE AN INDUSTRIAL GRADE RELIABILITY WIRE BONDING PACKAGE | | | |
| First Named Inventor/Applicant Name: | Wen-Chou Vincent Wang | | | |
| Filer: | CINDY H. SHU/Valerie Olsen | | | |
| Attorney Docket Number: | ALTRP100/A1198 | | | |
| Filed as Large Entity | | | | |
| Utility Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Utility Appl issue fee | 1501 | 1 | 1440 | 1440 |
| Extension-of-Time: | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-----------------------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Printed copy of patent - no color | 8001 | 2 | 3 | 6 |
| Total in USD (\$) | | | | 1446 |